Application No.: 09/851,231

AMENDMENTS TO THE CLAIMS

- 1. (Withdrawn)
- 2. (Withdrawn)
- 3. (Withdrawn
- 4. (Withdrawn))
- 5. (Withdrawn)
- 6. (Withdrawn)
- 7. (Withdrawn)
- 8. (Withdrawn)
- 9. (Withdrawn)
- 10. (Withdrawn)
- 11. (Currently Amended) An apparatus having at least one <u>a</u> sealed microchannel therein, comprising:

a first an etched substrate,

at least one an etched microchannel in said first etched substrate,

a second an annealed substrate positioned on said first etched substrate that covers said at least one etched microchannel in said first etched substrate,

a corresponding at least one <u>an</u> annealed microchannel in said second <u>annealed</u> substrate <u>immediately above said at least one covering said</u> etched microchannel in said <u>first etched</u> substrate, and

a bond connecting said <u>first etched</u> substrate and said <u>second annealed</u> substrate, wherein said <u>at least one etched</u> microchannel and said <u>at least one annealed</u> microchannel comprise said <u>at least one sealed</u> microchannel.

12. (Currently Amended) The apparatus of Claim 11, wherein said at least one sealed microchannel has no sharp corners therein annealed microchannel is a high temperature annealed microchannel annealed in the 600° to 800° range.



- 13. (Currently Amended) The apparatus of Claim 11, wherein said at least one etched microchannel in said first etched substrate and said corresponding at least one annealed microchannel in said second annealed substrate form a circular at least one sealed microchannel.
- 14. (Currently Amended) The apparatus of Claim 11, wherein said first etched substrate and said annealed substrate is are selected from the group consisting of glass members, glass and silicon members, glass and polymer members, and members selected from the group of glass, silicon and polymers.
- 15. (Previously Amended) The apparatus of Claim 11, wherein said bond comprises fusion or anodic bonding.
- 16. (Currently Amended) The apparatus of Claim 11, wherein said second substrate is selected from the group consisting of glass members, glass and silicon members, glass and polymer members, and members selected from the group of glass, silicon and polymers annealed microchannel has depth of about 10 µm and a width of about 20 µm and said annealed microchannel is a high temperature annealed microchannel annealed in the 600° to 800° range.